Package Drawing

Designator: ES

Type: 24-Contact QFN, 4 mm × 4 mm, 0.75 mm thickness, with Exposed Thermal Pad

For Reference Only – Not for Tooling Use
(Reference Allegro DWG-0000222 Rev. 4 or JEDEC MO-220WGGD.)
Dimensions in millimeters – NOT TO SCALE.
Exact case and lead configuration at supplier discretion within limits shown.

A Terminal #1 mark area

B Exposed thermal pad (reference only, terminal #1 identifier appearance at supplier discretion). Two variations shown: 2.70 mm × 2.70 mm and 2.10 mm × 2.10 mm

C Reference land pattern layout (reference IPC7351 QFN50P400X400X80-25W6M); all pads a minimum of 0.20 mm from all adjacent pads; adjust as necessary to meet application process requirements and PCB layout tolerances; when mounting on a multilayer PCB, thermal vias at the exposed thermal pad land can improve thermal dissipation (reference EIA/JEDEC Standard JESD51-5)

D Coplanarity includes exposed thermal pad and terminals

E Branding scale and appearance at supplier discretion.

Copyright 2021, Allegro MicroSystems drawings are for reference only; not for tooling use. Refer to the individual datasheet for information on a specific product package. Allegro MicroSystems reserves the right to make, from time to time, such departures from the detail specifications as may be required to permit improvements in the performance, reliability, or manufacturability of its products. Before placing an order, the user is cautioned to verify that the information being relied upon is current. The information included herein is believed to be accurate and reliable. However, Allegro MicroSystems assumes no responsibility for its use; nor for any infringement of patents or other rights of third parties which may result from its use.